ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: HP10007

REV$: E1

SUN REV: 619 (Locally Modified)

LAYER NAME = Top Overlay

PLOT NAME = Top Overlay

GENERATED: 1/31/2014 4:08:47 PM

TEXAS INSTRUMENTS
<table>
<thead>
<tr>
<th>ALL ARTWORK VIEWED FROM TOP SIDE</th>
<th>BOARD #</th>
<th>HPID007</th>
<th>REV  E1</th>
<th>SUN  REV  619 [Locally Modified]</th>
</tr>
</thead>
<tbody>
<tr>
<td>LAYER NAME = Top Solder</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME  = Top Solder Mask</td>
<td>GENERATED: 1/31/2014 4:08:48 PM</td>
<td>TEXAS INSTRUMENTS</td>
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<tr>
<td>ALL ARTWORK VIEWED FROM TOP SIDE</td>
<td>BOARD #: HP10077</td>
<td>REV: E1</td>
<td>SUN REV: 619 [Locally Modified]</td>
<td></td>
</tr>
<tr>
<td>----------------------------------</td>
<td>------------------</td>
<td>--------</td>
<td>--------------------------------</td>
<td></td>
</tr>
<tr>
<td>LAYER NAME = Bottom Overlay</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Bottom Overlay</td>
<td>GENERATED 1/31/2014 4:08:52 PM</td>
<td>TEXAS INSTRUMENTS</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
### Drill Table

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Hit Count</th>
<th>Tool Size</th>
<th>Plated</th>
<th>Hole Type</th>
</tr>
</thead>
<tbody>
<tr>
<td>D</td>
<td>5</td>
<td>16mil (0.406mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td></td>
<td>1</td>
<td>28mil (0.711mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td></td>
<td>6</td>
<td>40mil (1.016mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td></td>
<td>12 Total</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

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**ALL ARTWORK VIEWED FROM TOP SIDE**  
**BOARD #: HPIK007**  
**REV: E1**  
**SUN REV: 619 [Locally Modified]**

**LAYER NAME = Drill Drawing**

**PLOT NAME = Drill Drawing**  
**GENERATED: 1/31/2014  4:08:53 PM**  
**TEXAS INSTRUMENTS**
<table>
<thead>
<tr>
<th>ALL ARTWORK VIEWED FROM TOP SIDE</th>
<th>BOARD #: HP10007</th>
<th>REV: E1</th>
<th>SUN REV: 619 [Locally Modified]</th>
</tr>
</thead>
<tbody>
<tr>
<td>LAYER NAME = M2 Board Dimensions</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Board Dimensions</td>
<td>GENERATED: 1/31/2014 4:08:55 PM</td>
<td></td>
<td>TEXAS INSTRUMENTS</td>
</tr>
</tbody>
</table>
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